| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 1 | 2 | ("6555417").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/01/09 14:43 |
| - | 1986 | MEMS and cavity | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:50 |
| - | 128 | (438/55).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:26 |
| - | 188 | (438/33).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:27 |
| - | 272 | (438/64).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:27 |
| - | 168 | (438/66).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:28 |
| - | 2320 | (438/106).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:29 |
| - | 664 | (438/126).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:30 |
| - | 1045 | (438/118).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:31 |
| - | 271 | (438/110).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:32 |
| - | 202 | (438/51).CCLS. | USPAT; US-PGPUB; EPO; JPO; IBM_TDB | 2003/10/22 17:32 |
| - | 593 | (438/15).CCLS. | USPAT; US-PGPUB; EPO; JPO; IBM_TDB | 2003/10/22 17:32 |
| - | 742 | (216/2).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:47 |
| - | 1737 | MEMS and (cavity or cavities) and (cap or capped or capping or seal$3 or cover$3 or encapsulat$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:37 |

| | | | | |
|---|---|---|---|---|
| - | 1436 | MEMS and (cavity or cavities) and (cap or capped or capping or seal$3 or cover$3 or encapsulat$3) and (cut$3 or etch$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:47 |
| | 215 | (MEMS and (packag$3)).ab. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:39 |
| | 63 | (MEMS and (cavity or cavities) and (cap or capped or capping or seal$3 or cover$3 or encapsulat$3)).ab. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:47 |
| - | 286 | (216/11).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:29 |
| - | 425 | (216/17).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:48 |
| | 909 | (216/20).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:49 |
| | 644 | (216/24).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:50 |
| - | 2311 | MEMS and (cavity or recess) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:17 |
| - | 480 | (216/33).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:56 |
| - | 123 | (216/36).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:54 |
| - | 10 | ((216/33).CCLS.) and mems | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 17:54 |
| - | 80 | (((438/25).CCLS.) or ((438/55).CCLS.) or ((438/33).CCLS.) or ((438/64).CCLS.) or ((438/66).CCLS.) or ((438/106).CCLS.) or ((438/127).CCLS.) or ((438/126).CCLS.) or ((438/118).CCLS.) or ((438/110).CCLS.) or ((438/51).CCLS.) or ((438/15).CCLS.)) and MEMS | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:00 |
| | 141 | ((216/2).CCLS.) or ((216/11).CCLS.) or ((216/17).CCLS.) or ((216/20).CCLS.) or ((216/24).CCLS.) or ((216/33).CCLS.) or ((216/36).CCLS.)) and MEMS | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/01/09 12:46 |

| - | 215 | (((((438/25).CCLS.) or ((438/55).CCLS.) or ((438/33).CCLS.) or ((438/64).CCLS.) or ((438/66).CCLS.) or ((438/106).CCLS.) or ((438/127).CCLS.) or ((438/126).CCLS.) or ((438/118).CCLS.) or ((438/110).CCLS.) or ((438/51).CCLS.) or ((438/15).CCLS.)) and MEMS) or (((((216/2).CCLS.) or ((216/11).CCLS.) or ((216/17).CCLS.) or ((216/20).CCLS.) or ((216/24).CCLS.) or ((216/33).CCLS.) or ((216/36).CCLS.)) and MEMS) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:00 |
| - | 20 | ((wafer adj bonding) or (wafer adj cap$4)).ti. and MEMS | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:18 |
| - | 1567 | MEMS and (cavity or recess) and cap$4 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:37 |
| - | 49 | MEMS and (cavity or recess) and (wafer adj cap$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:20 |
| - | 99 | MEMS and (cavity or recess) and (wafer near3 cap$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:27 |
| - | 27 | (MEMS and package).ti. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:28 |
| - | 803 | (257/433).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:31 |
| - | 816 | (257/443).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:32 |
| - | 1596 | ((257/433).CCLS.) or ((257/443).CCLS.) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:33 |
| - | 561 | (257/466).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:34 |
| - | 334 | MEMS and (cavity or recess) and cap$4 and dic$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 18:37 |
| - | 2 | ("5323051").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/22 19:07 |
| - | 154 | (438/25).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/01/08 15:17 |

| | | | | |
|---|---:|---|---|---|
| – | 647 | MEMS and (cavity or cavities) and (cap or capped or capping) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/08 15:17 |
| – | 111 | MEMS with (cap or capped or capping) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/08 15:40 |
| – | 56 | MEMS and (cap or capped or capping) same (diced or dicing or dice) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/08 15:53 |
| – | 15 | (MEMS and (cap or capped or capping) and (diced or dicing or dice)).ab. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/09 10:25 |
| – | 11 | ("4742432" \| "4889587" \| "5230759" \| "5656776" \| "5798557" \| "5824177" \| "5915168" \| "5923995" \| "6136212" \| "6255741" \| "6379988").PN. | USPAT | 2004/01/08 15:47 |
| – | 886 | (438/108).CCLS. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/08 15:54 |
| – | 674 | (438/113).CCLS. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/08 15:54 |
| – | 920 | (438/127).CCLS. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/08 15:55 |
| – | 62 | (MEMS and (cap or capped or capping)).ab. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/09 12:48 |
| – | 18 | (wafer adj cap$4).ab. and MEMS | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/09 12:46 |
| – | 23 | (((216/2).CCLS.) or ((216/11).CCLS.) or ((216/17).CCLS.) or ((216/20).CCLS.) or ((216/24).CCLS.) or ((216/33).CCLS.) or ((216/36).CCLS.)) and MEMS and (cap or capping) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/09 12:47 |
| – | 21 | ((MEMS or microstructure$1 or micromechanical or microelectromechanical) and (cap or capped or capping)).ti. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/01/09 12:49 |